Abstract

The invention relates to a mounting apparatus for handling of a structured substrate (1) which has structures (3) with a soft material layer (5) for accommodating the structured substrate (5) on a receiving surface (5o), the structures (3) of the structured substrate (1) being able to be taken at least partially into the material layer (5), characterized in that there are fixing means for fixing of the structured substrate (1) on the receiving surface.

Furthermore this invention relates to a corresponding method and a use of the mounting apparatus for thin substrates with a thickness d less than 100 μm.

Figure 3 in this respect